

Amendments to the Claims:

Cancel claims 14-30, without prejudice.

The following listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1. (currently amended) A method of manufacturing a transparent substrate that is to have a transparent conductive film formed on a surface thereof, ~~characterized by~~ comprising:

controlling a surface smoothness of the surface of the transparent substrate to satisfy

$0 \text{ nm} \leq R_z \leq 4 \text{ nm}$; and

controlling a surface smoothness of a surface of the transparent conductive film to satisfy

$0 \text{ nm} \leq R_z \leq 8 \text{ nm}$.

2. (currently amended) [[A]] The method of manufacturing a transparent substrate as claimed in claim 1, ~~characterized in that~~ wherein the controlling of the surface smoothness is carried out by omitting polishing of the surface of the transparent substrate.

3. (currently amended) [[A]] The method of manufacturing a transparent substrate as claimed in claim 2, ~~characterized in that~~ wherein the surface of the transparent substrate is subjected to etching using an acidic aqueous solution containing hydrofluoric acid or an alkaline aqueous solution containing potassium hydroxide or sodium hydroxide.

4. (currently amended) [[A]] The method of manufacturing a transparent substrate as claimed in claim 3, ~~characterized in that~~ wherein after the etching has been carried out, the surface of the transparent substrate is subjected to alkaline washing comprising washing using an alkaline liquid.

5. (currently amended) [[A]] The method of manufacturing a transparent substrate as claimed in claim 1, ~~characterized in that~~ wherein the controlling of the surface smoothness is carried out mainly by polishing the surface of the transparent substrate.

6. (currently amended) [[A]] The method of manufacturing a transparent substrate as claimed in claim 5, ~~characterized in that~~ wherein the polishing of the surface of the transparent substrate is carried out using a cerium oxide powder having a predetermined mean particle diameter, and after the polishing of the surface of the transparent substrate has been carried out, the surface of the transparent substrate is washed using a mixed liquid of sulfuric acid and ascorbic acid or a mixed liquid of nitric acid and ascorbic acid, and after the surface of the transparent substrate has been washed, the surface of the transparent substrate is subjected to etching using an acidic aqueous solution containing hydrofluoric acid or an alkaline aqueous solution containing potassium hydroxide or sodium hydroxide.

7. (currently amended) [[A]] The method of manufacturing a transparent substrate as claimed in claim 6, ~~characterized in that~~ wherein after the etching has been carried out, the surface of the transparent substrate is subjected to alkaline washing comprising washing using an alkaline liquid.

8. (currently amended) [[A]] The method of manufacturing a transparent substrate as claimed in claim 5, ~~characterized in that~~ wherein the polishing of the surface of the transparent substrate is carried out using a cerium oxide powder having a predetermined mean particle diameter, and is then further carried out using a cerium oxide powder having a mean particle diameter lower than the predetermined mean particle diameter.

9. (currently amended) [[A]] The method of manufacturing a transparent substrate as claimed in claim 8, ~~characterized in that~~ wherein after the polishing of the surface of the transparent substrate has been carried out, the surface of the transparent substrate is washed using a mixed liquid of sulfuric acid and ascorbic acid or a mixed liquid of nitric acid and ascorbic acid.

10. (currently amended) [[A]] The method of manufacturing a transparent substrate as claimed in claim 9, ~~characterized in that~~ wherein after the surface of the transparent substrate has been washed, the surface of the transparent substrate is subjected to alkaline washing comprising washing using an alkaline liquid.

11. (currently amended) [[A]] The method of manufacturing a transparent substrate as claimed in claim 9, ~~characterized in that~~ wherein after the surface of the transparent substrate has been washed, the surface of the transparent substrate is subjected to etching using an acidic aqueous solution containing hydrofluoric acid or an alkaline aqueous solution containing potassium hydroxide or sodium hydroxide.

12. (currently amended) [[A]] The method of manufacturing a transparent substrate as claimed in claim 8, ~~characterized in that~~ wherein after the polishing of the surface of the transparent substrate has been carried out, the surface of the transparent substrate is subjected to etching using an acidic aqueous solution containing hydrofluoric acid or an alkaline aqueous solution containing potassium hydroxide or sodium hydroxide.

13. (currently amended) [[A]] The method of manufacturing a transparent substrate as claimed in claim 11, ~~characterized in that~~ wherein after the etching has been carried out, the surface of the transparent substrate is subjected to alkaline washing comprising washing using an alkaline liquid.

14.-30. (canceled)